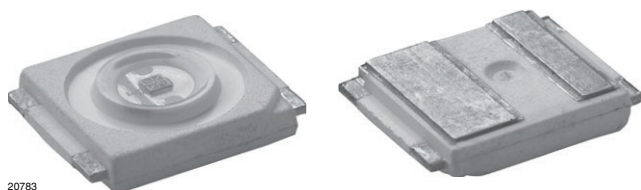


High Power Infrared Emitting Diode, 850 nm, Surface Emitter Technology



DESCRIPTION

As part of the [SurfLight™](#) portfolio, the VSMY7852X01 is an infrared, 850 nm emitting diode based on surface emitter technology with high radiant power and high speed, molded in low thermal resistance Little Star package. A 20 mil chip provides outstanding low forward voltage and allows DC operation of the device up to 250 mA.

APPLICATIONS

- Infrared illumination for CMOS cameras (CCTV)
- Machine vision IR data transmission

FEATURES

- Package type: surface-mount
- Package form: Little Star®
- Dimensions (L x W x H in mm): 6.0 x 7.0 x 1.5
- Peak wavelength: $\lambda_p = 850$ nm
- High reliability
- High radiant power
- High radiant intensity
- Angle of half intensity: $\phi = \pm 60^\circ$
- Low forward voltage
- Designed for high drive currents: up to 250 mA DC and up to 1.5 A pulses
- Low thermal resistance: $R_{thJP} = 15$ K/W
- Floor life: 1 year, MSL 2, according to J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT

PRODUCT SUMMARY

COMPONENT	I_e (mW/sr)	ϕ (deg)	λ_p (nm)	t_r (ns)
VSMY7852X01	55	± 60	850	8

Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY7852X01-GS08	Tape and reel	MOQ: 2000 pcs, 2000 pcs/reel	Little Star

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_R	5	V
Forward current		I_F	250	mA
Peak forward current	$t_p/T = 0.5$, $t_p = 100 \mu\text{s}$	I_{FM}	500	mA
Surge forward current	$t_p = 100 \mu\text{s}$	I_{FSM}	1.5	A
Power dissipation		P_V	500	mW
Junction temperature		T_j	125	$^\circ\text{C}$
Operating temperature range		T_{amb}	-40 to +100	$^\circ\text{C}$
Storage temperature range		T_{stg}	-40 to +100	$^\circ\text{C}$
Soldering temperature	According to Fig. 7, J-STD-20	T_{sd}	260	$^\circ\text{C}$
Thermal resistance junction-to-pin	According to J-STD-051, soldered on PCB	R_{thJP}	15	K/W

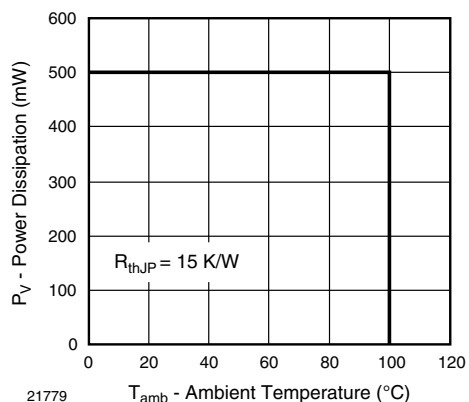


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

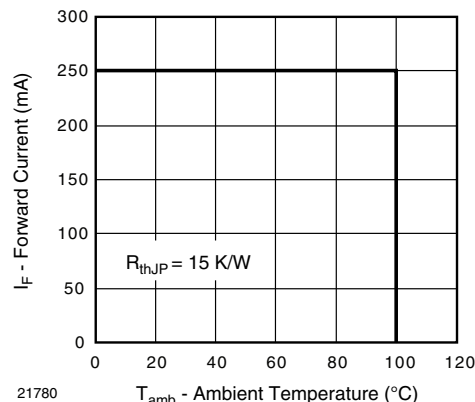


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS ($T_{amb} = 25 \text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 250 \text{ mA}$, $t_p = 10 \text{ ms}$	V_F	-	1.7	2.0	V
Temperature coefficient of V_F	$I_F = 1 \text{ mA}$	TK_{VF}	-	-1.5	-	mV/K
Reverse current	$V_R = 5 \text{ V}$	I_R	Not designed for reverse operation			μA
Radiant intensity	$I_F = 250 \text{ mA}$, $t_p = 10 \text{ ms}$	I_e	30	55	90	mW/sr
Radiant power	$I_F = 250 \text{ mA}$, $t_p = 20 \text{ ms}$	ϕ_e	-	130	-	mW
Temperature coefficient of ϕ_e	$I_F = 1 \text{ A}$	TK_{ϕ_e}	-	-0.5	-	%/K
Angle of half intensity		ϕ	-	± 60	-	deg
Peak wavelength	$I_F = 250 \text{ mA}$	λ_p	-	850	-	nm
Spectral bandwidth	$I_F = 250 \text{ mA}$	$\Delta\lambda$	-	30	-	nm
Temperature coefficient of λ_p	$I_F = 250 \text{ mA}$	TK_{λ_p}	-	0.2	-	nm/K
Rise time	$I_F = 250 \text{ mA}$	t_r	-	8	-	ns
Fall time	$I_F = 250 \text{ mA}$	t_f	-	10	-	ns

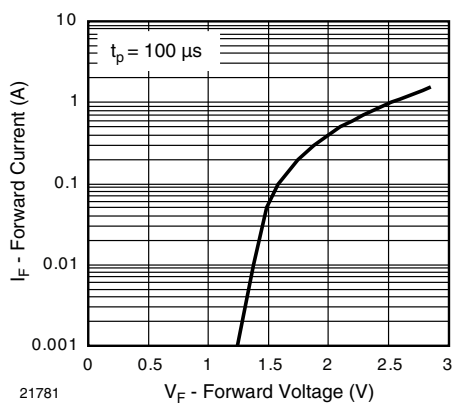
BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)


Fig. 3 - Forward Current vs. Forward Voltage

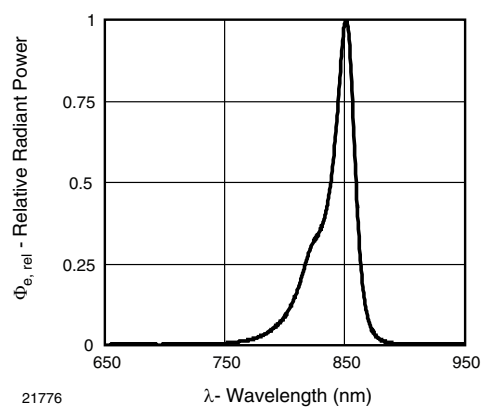


Fig. 5 - Relative Radiant Power vs. Wavelength

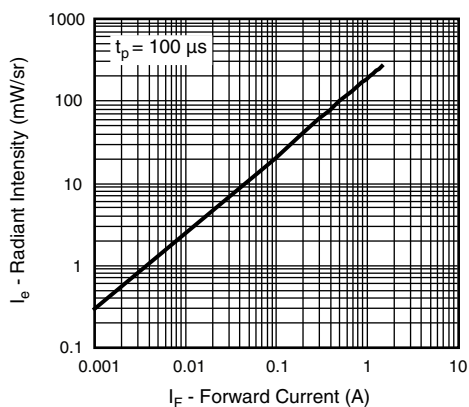


Fig. 4 - Radiant Intensity vs. Forward Current

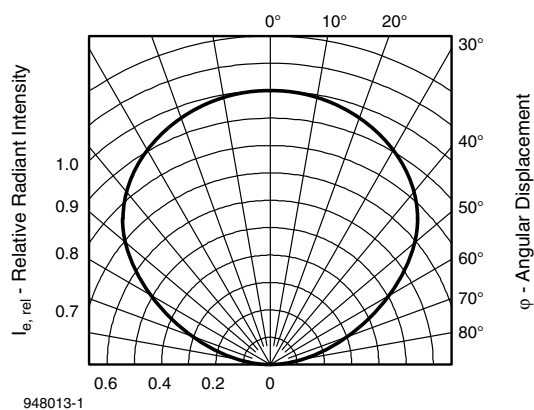
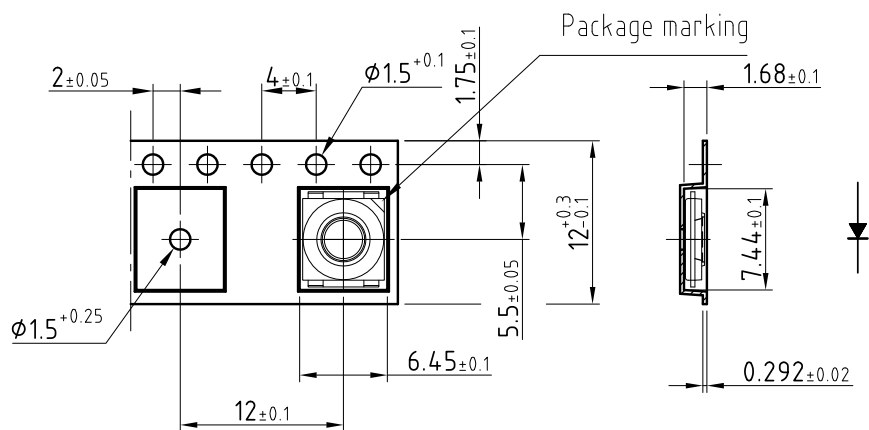
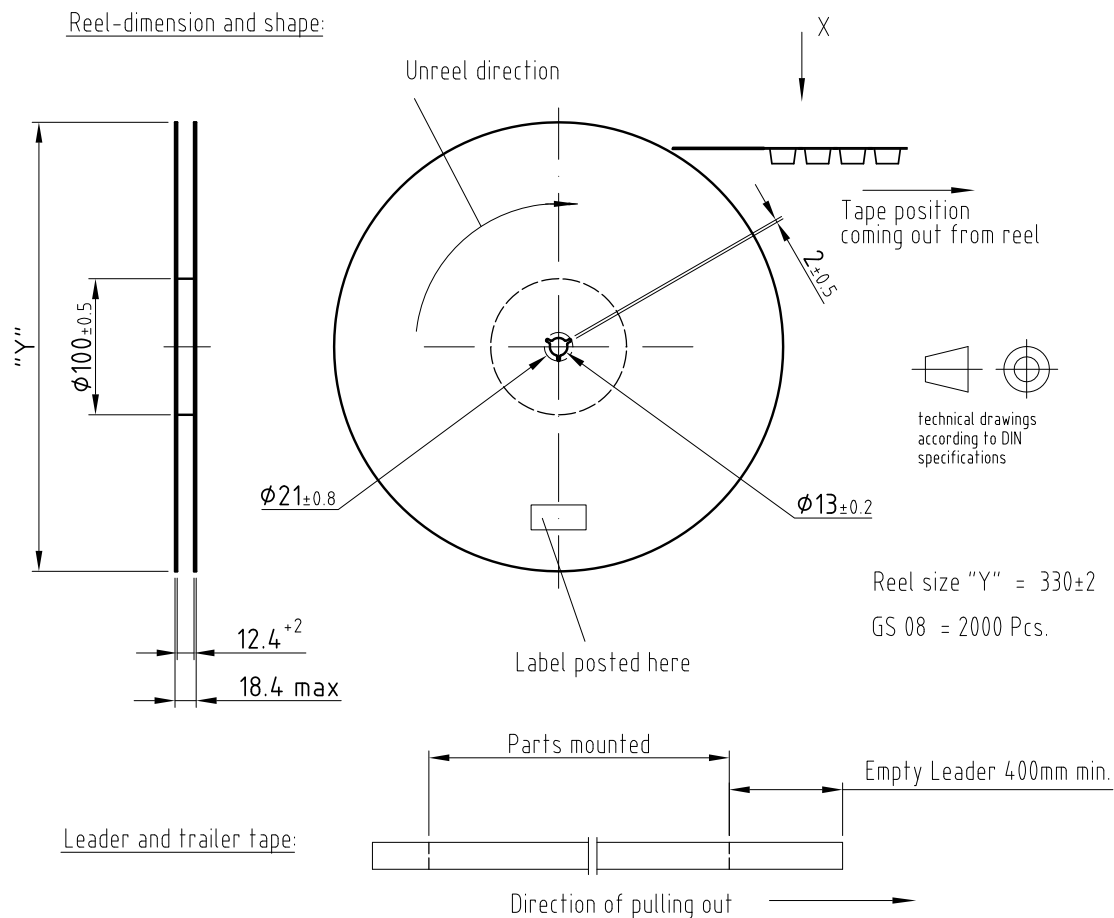


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

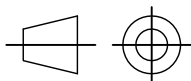
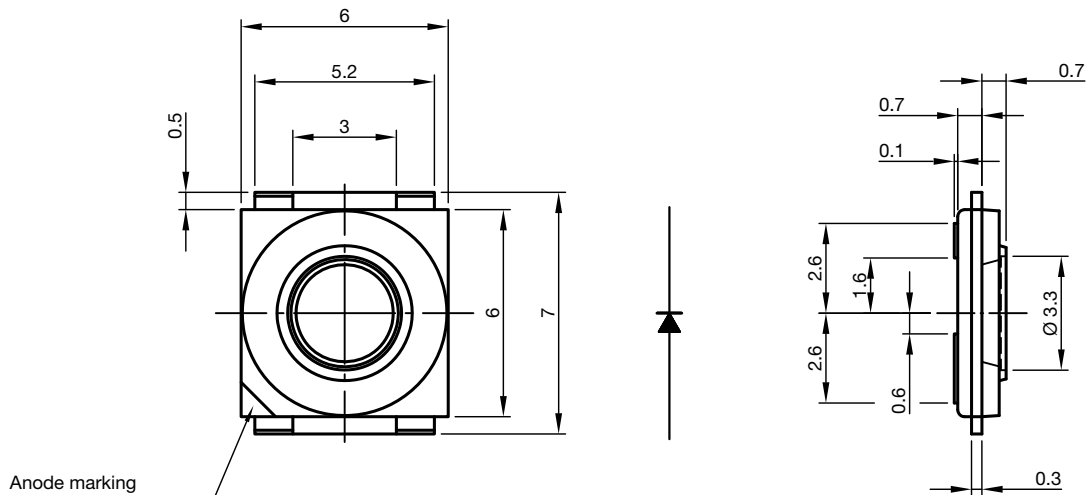
TAPING DIMENSIONS in millimeters


Drawing-No.: 9.800-5094.01-4

Issue: 3; 22.01.08

20846

PACKAGE DIMENSIONS in millimeters



technical drawings
according to DIN
specifications

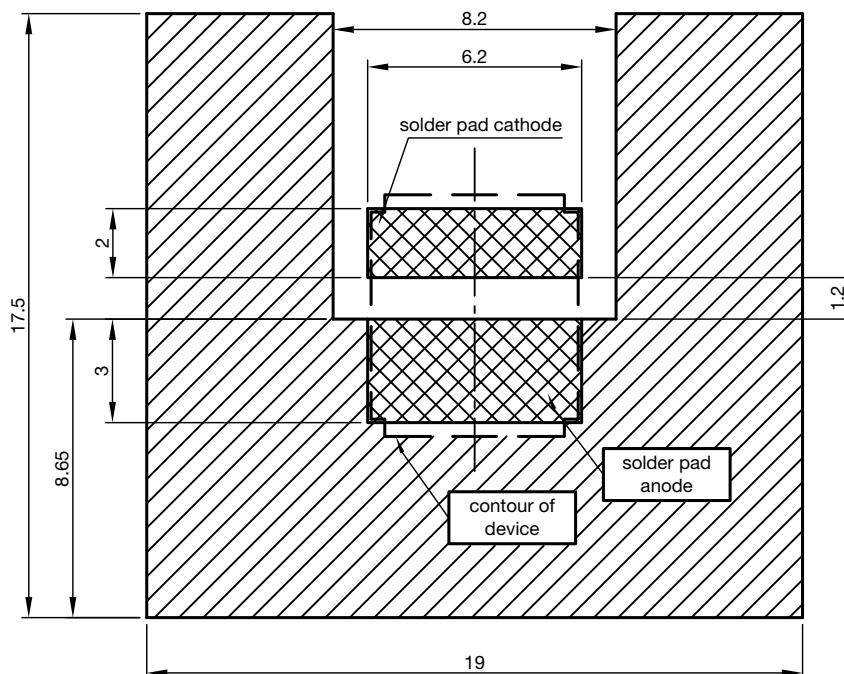
Recommended solder pad



Recommended area for heat sink
connected with anode pad



Not indicated tolerances ± 0.1



Drawing-No.: 6.541-5076.01-4
Issue: 3; 22.10.14

SOLDER PROFILE

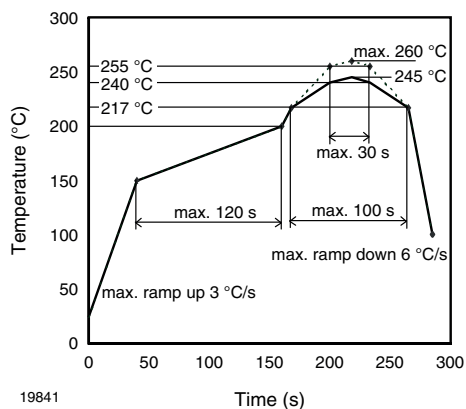


Fig. 7 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020 for Preconditioning According to JEDEC®, Level 2

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 1 year

Conditions: $T_{amb} < 30\text{ °C}$, $RH < 60\%$

Moisture sensitivity level 2, according to J-STD-020B

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), $RH < 5\%$.



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